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(19) **United States**(12) **Patent Application Publication** (10) **Pub. No.: US 2023/0232570 A1**
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ACOUSTICAL BAFFLES**(52) **U.S. CL.**
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G06F 1/18 (2006.01)(57) **ABSTRACT**

A computing chassis, including hard disk drives positioned at a first end of the chassis; a fan module positioned at a second end of the chassis; a first baffle having acoustic absorbing material, the first baffle extending between a first and a second side of the chassis, wherein the first and second ends of the chassis extend between the first and the second ends of the chassis, the first baffle spaced-apart from the fan module a first distance; a second baffle having acoustic absorbing material, the second baffle extending between the first and the second side of the chassis, the second baffle spaced-apart from the fan module a second distance greater than the first distance, wherein the first and the second baffle extend between the first and second sides of the chassis perpendicular to an airflow, and the acoustic absorbing material of the baffles attenuate acoustic waves.

